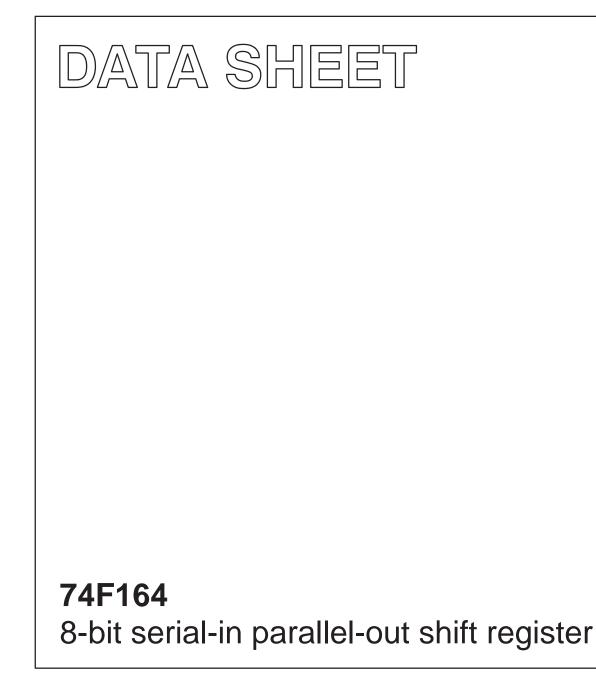
INTEGRATED CIRCUITS



Product specification Supersedes data of 1995 Sep 22

2000 Dec 18



Philips Semiconductors

74F164

FEATURES

- Gated serial data inputs
- Typical shift frequency of 100MHz
- Asynchronous Master Reset
- Buffered clock and data inputs
- Fully synchronous data transfer
- Industrial temperature range available (-40 to +85 °C)

DESCRIPTION

The 74F164 is an 8-bit edge-triggered shift register with serial data entry and an output from each of the eight stages. Data is entered through one of two inputs (Dsa, Dsb); either input can be used as an active High enable for data entry through the other input. Both inputs must be connected together or an unused input must be tied High.

Data shifts one place to the right on each Low-to-High transition of the clock (CP) input, and enters into Q0 the logical AND of the two data inputs (Dsa, Dsb) that existed one setup time before the rising edge. A Low level on the Master Reset (\overline{MR}) input overrides all other inputs and clears the register asynchronously, forcing all outputs Low.

ORDERING INFORMATION

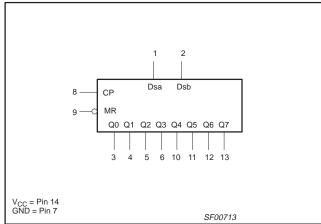
	ORDER CO	DDE	DRAWING
DESCRIPTION	COMMERCIAL RANGE V _{CC} = 5 V \pm 10%, T _{amb} = 0 to +70 °C	INDUSTRIAL RANGE V _{CC} = 5 V \pm 10%, T _{amb} = -40 to +85 °C	NUMBER
14-pin plastic DIP	74F164N	I74F164N	SOT27-1
14-pin plastic SO	74F164D	I74F164D	SOT108-1

INPUT AND OUTPUT LOADING AND FAN OUT TABLE

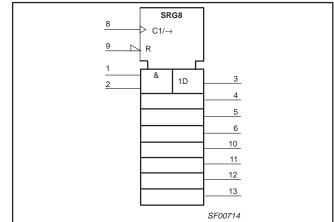
PINS	DESCRIPTION	74F (U.L.) HIGH / LOW	LOAD VALUE HIGH / LOW
Dsa, Dsb	Data inputs	1.0 / 1.0	20 µA / 0.6 mA
CP	Clock pulse input (active rising edge)	1.0 / 1.0	20 µA / 0.6 mA
MR	Master reset input (active-Low)	1.0 / 1.0	20 µA / 0.6 mA
Q0 – Q7	Data outputs	50 / 33	1.0 mA / 20 mA

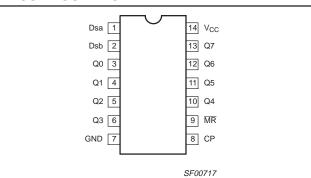
One (1.0) FAST unit load is defined as: 20 μ A in the High state and 0.6 mA in the Low state.

LOGIC SYMBOL



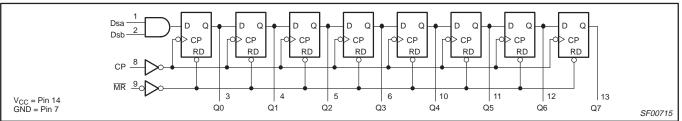
IEC/IEEE SYMBOL





TYPE	TYPICAL f _{max}	TYPICAL SUPPLY CURRENT (TOTAL)
74F164	100MHz	33 mA

LOGIC DIAGRAM



FUNCTION TABLE

	INP	INPUTS			OUTPU							OPERATING MODE
MR	СР	Dsa	Dsb	Q0	Q1	Q2	Q3	Q4	Q5	Q6	Q7	
L	Х	Х	Х	L	L	L	L	L	L	L	L	Reset (Clear)
Н	↑	I	I	L	q0	q1	q2	q3	q4	q5	q6	
Н	↑	I	h	L	q0	q1	q2	q3	q4	q5	q6	Shift
Н	↑	h	I	L	q0	q1	q2	q3	q4	q5	q6	
Н	\uparrow	h	h	Н	q0	q1	q2	q3	q4	q5	q6	

H = High voltage level

h = High voltage level one setup time prior to the Low-to-High clock transition.

L = Low voltage level

I = Low voltage level one setup time prior to the Low-to-High clock transition.

qn = Lower case letter indicate the state of the referenced output one setup time prior to the Low-to-High clock transition.

 \dot{X} = Don't care \uparrow = Low-to-Hig

 \uparrow = Low-to-High clock transition

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device.

SYMBOL	PARAMETER		RATING	UNIT
V _{CC}	Supply voltage		-0.5 to +7.0	V
V _{IN}	Input voltage		-0.5 to +7.0	V
I _{IN}	Input current	-30 to +5	mA	
V _{OUT}	Voltage applied to output in High output state		–0.5 to V _{CC}	V
I _{OUT}	Current applied to output in Low output state		40	mA
<u>т</u>	On proting free pir temperature renge	Commercial Range	0 to +70	°C
T _{amb}	Operating free-air temperature range	Industrial Range	-40 to +85	
T _{stg}	Storage temperature range	-65 to +150	°C	

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER			LIMIT		UNIT
			MIN	NOM	MAX	
V _{CC}	Supply voltage		4.5	5.0	5.5	V
V _{IH}	High-level input voltage		2.0			V
V _{IL}	Low-level input voltage				0.8	V
I _{lk}	Input clamp current				-18	mA
I _{OH}	High-level output current				-1	mA
I _{OL}	Low-level output current				20	mA
т	Operating free-air temperature range	Commercial Range	0		+70	°C
T _{amb}	Operating nee-an temperature range	Industrial Range	-40		+85	\neg

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	DADAMETED	TEST	TEST				
SYMBOL	PARAMETER	CONDITION	MIN	TYP ²	MAX	1	
Maria	High-level output voltage	$V_{CC} = MIN, V_{IL} = MAX,$	±10%V _{CC}	2.5			V
V _{OH}	nigh-ievel output voltage	$V_{IH} = MIN, I_{OH} = MAX$	±5%V _{CC}	2.7	3.4		V
V _{OL}	Low-level output voltage	$V_{CC} = MIN, V_{IL} = MAX,$ $V_{IH} = MIN, I_{OL} = MAX$	±10%V _{CC}		0.30	0.50	V
		$V_{IH} = MIN, I_{OL} = MAX$	±5%V _{CC}		0.30	0.50	V
V _{IK}	Input clamp voltage	$V_{CC} = MIN, I_I = I_{IK}$	•		-0.73	-1.2	V
lj	Input current at maximum input voltage	$V_{CC} = MAX, V_I = 7.0 V$				100	μΑ
I _{IH}	High-level input current	$V_{CC} = MAX, V_I = 2.7 V$				20	μΑ
I _{ILL}	Low-level input current	$V_{CC} = MAX, V_I = 0.5 V$				-0.6	mA
I _{OS}	Short-circuit output current ³	V _{CC} = MAX	-60		-150	mA	
I _{CC}	Supply current (total) ⁴	V _{CC} = MAX			33	55	mA

Notes to DC electrical characteristics

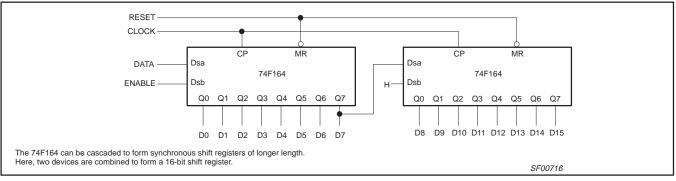
1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

2. All typical values are at $V_{CC} = 5 \text{ V}$, $T_{amb} = 25 \text{ }^{\circ}\text{C}$.

3. Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter test, I_{OS} tests should be performed last.

4. Measure I_{CC} with the serial inputs grounded, the clock input at 2.4 V, and a momentary ground, then applied to Master Reset, and all outputs open.

APPLICATION



AC ELECTRICAL CHARACTERISTICS

						LI	MITS	-		
SYMBOL	PARAMETER	TEST CONDITION		nb = +25 ′cc = 5 ′ L = 50 p L = 500	V F	T _{amb} = 0 f V _{CC} = +5 C _L = 5 R _L = 5	to +70 °C 5 V±10% 50 pF 500 Ω	V _{CC} = +{ C _L = {) to +85 °C 5 V±10% 50 pF 500 Ω	UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	1
f _{max}	Maximum clock frequency	Waveform 1	80	100		80		80		MHz
t _{PLH} t _{PHL}	Propagation delay CP to Qn	Waveform 1	3.0 5.0	5.0 7.0	8.0 10.0	2.5 5.0	9.0 11.0	2.5 5.0	9.0 11.0	ns
t _{PHL}	Propagation delay MR to Qn	Waveform 3	5.5	7.5	10.5	5.5	11.5	5.5	11.5	ns

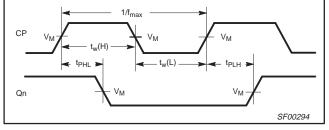
AC SETUP REQUIREMENTS

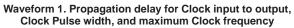
						LI	MITS			
SYMBOL	PARAMETER	TEST CONDITION	V C	_{nb} = +25 ′cc = 5 \ ∟ = 50 p ∟ = 500	V F	T _{amb} = 0 f V _{CC} = +5 C _L = 5 R _L = 5	5 V±10%	V _{CC} = +{ C _L = {		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _s (H) t _S (L)	Setup time, High or Low D _n to CP	Waveform 2	7.0 7.0			7.0 7.0		7.0 7.0		ns
t _h (H) t _h (L)	Hold time, High or Low D _n to CP	Waveform 2	1.0 1.0			2.0 2.0		2.0 2.0		ns
t _w (H) t _w (L)	CP Pulse width High or Low	Waveform 1	4.0 7.0			4.0 7.0		4.0 7.0		ns
t _w (L)	MR Pulse wicth Low	Waveform 3	7.0			7.0		7.0		ns
t _{REC}	Recovery time MR to CP	Waveform 3	7.0			7.0		7.0		ns

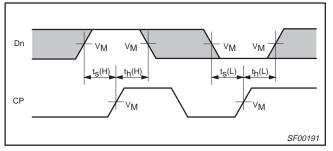
AC WAVEFORMS

For all waveforms, $V_M = 1.5$ V.

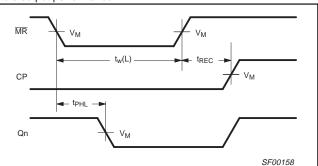
The shaded areas indicate when the input is permitted to change for predictable output performance.







Waveform 2. Data setup and hold times

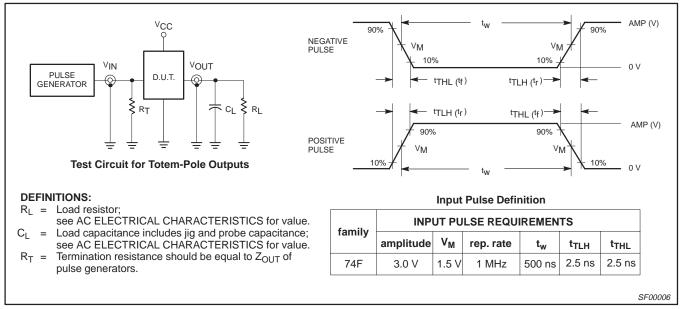


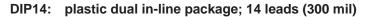
Waveform 3. Master Reset pulse width, Master Reset to output delay and Master Reset to Clock recovery time

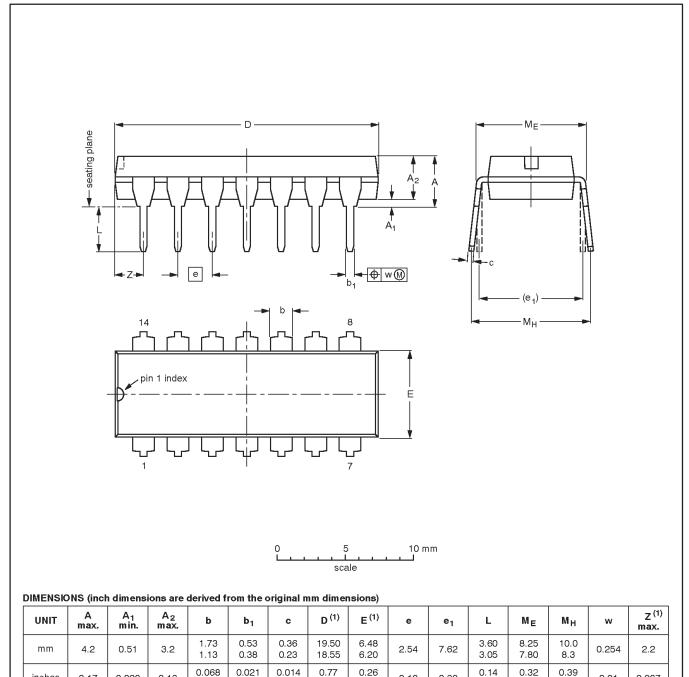
Product specification

74F164

TEST CIRCUIT AND WAVEFORMS







Note

inches

0.17

0.020

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

0.044

0.015

0.009

0.13

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT27-1	050G04	MO-001	SC-501-14			-95-03-11 99-12-27

0.24

0.73

0.10

0.30

0.12

0.31

0.33

0.01

0.087

SOT27-1

OUTLINE

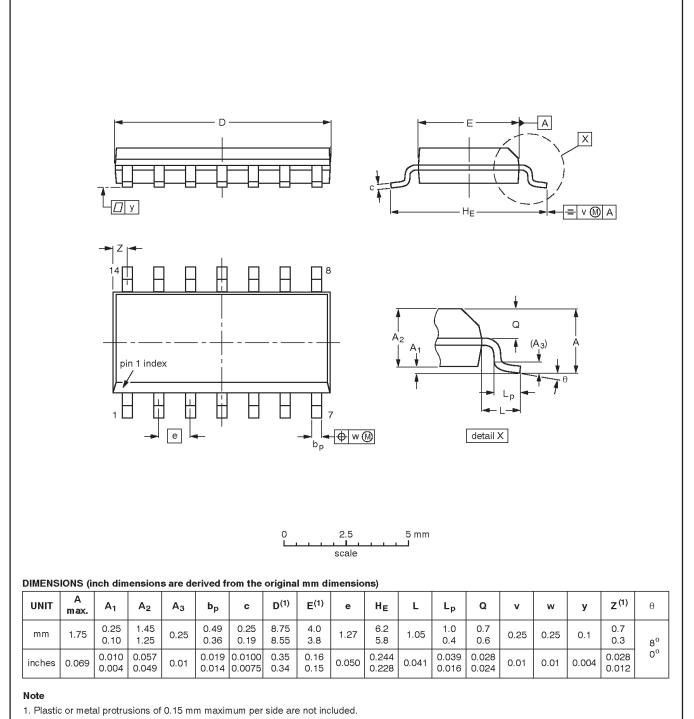
VERSION

SOT108-1

IEC

076E06

SO14: plastic small outline package; 14 leads; body width 3.9 mm



74F164

SOT108-1

EIAJ

EUROPEAN

PROJECTION

-E--

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ISSUE DATE

97-05-22

99-12-27

REFERENCES

JEDEC

MS-012

74F164

NOTES

74F164

Data sheet status

Data sheet status	Product status	Definition ^[1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued datasheet before initiating or completing a design.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition - Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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